MOUNTING METHOD FOR IMAGE SENSOR AND ADHESIVE TAPE USED THEREFOR

ABSTRACT OF THE DISCLOSURE

Provided is a mounting method for an image sensor capable of applying solder reflow in a state where an adhesive tape is adhered on the light receiving side of the image sensor in a mounting process for an image sensor using a solid-state image pick-up device and protecting the light receiving side of the image sensor even during solder reflow, and a protective adhesive tape used therefore. It is characterized by that an adhesive tape using a polyimide film as a base material is adhered on the light receiving section side of the image sensor and, by heating 170°C or higher in the state, terminals of the image sensor are connected by solder reflow to a substrate side, and at least silicone material is used as a constituent of an adhesive agent for the adhesive tape.

FIG. 1